

REMARKS

This Supplemental Amendment is being filed in addition to the Response (i.e., filed on October 7, 2009) to the final Office Action dated July 7, 2009, and the Advisory Action dated September 18, 2009, issued in connection with the above-identified application. Claims 1-11 are pending in the present application. With this Supplemental Amendment, independent claim 1 has been amended, and no new matter has been introduced. Favorable reconsideration is respectfully requested.

In the Office Action, claims 1-11 have been rejected under 35 U.S.C. 102(b) as being anticipated by Keiichi Murakami (Japanese Application No. 2000-332387, hereafter “Murakami”).

An interview was conducted between Examiner Phan and the Applicants’ representative on October 29, 2009. During the interview, the present invention as recited in independent claim 1 and the cited prior art were discussed in detail. Additionally, the arguments presented in the response filed on October 7, 2009 were also discussed.

In particular, it was noted that the cited prior art fails to disclose or suggest at least “introducing outside air into a reduced pressure and environment while maintaining the pressed state and the curing temperature,” and “reducing the pressure applied to the smoothing plate while maintaining the curing temperature,” as recited in independent claim 1.

At the conclusion of the interview, it was agreed that claim 1 could be amended to distinguish from the prior art by adding a specific temperature or a temperature range to the claims. Accordingly, this Supplemental Amendment amends independent claim 1 to add a temperature range, as suggested by the Examiner. Specifically, as amended, independent claim 1 recites the following features:

“[a] method for manufacturing a printed wiring board which includes forming a thermosetting resin layer so as to fill spaces between circuit patterns formed on a surface of the printed wiring board, heating and curing the resin layer, and then polishing the cured resin layer covering the circuit patterns, thereby exposing the circuit patterns, wherein the step of heating and curing the resin layer comprises:

maintaining the resin layer at a non-curable temperature range between 100°C-140°C where the resin layer is pressed via a smoothing plate in a reduced pressure environment;

heating the resin layer in the pressed state to a curing temperature at which the resin layer is cured;

introducing outside air into the reduced pressure environment while maintaining the pressed state and the curing temperature;

reducing the pressure applied to the smoothing plate while maintaining the curing temperature; and

cooling the resin layer,

wherein a metallic foil with a roughened surface facing the resin layer is superposed on the resin layer.” (Emphasis added).

In the Office Action, the Examiner relies on Murakami for disclosing or suggesting all the features recited in independent claim 1. However, as agreed during the interview, Murakami fails to disclose or suggest the use of a temperature range as part of a method of manufacturing a printed circuit board.

Additionally, as noted above, independent claim 1 has been amended to point out that the resin layer is maintained at a non-curable temperature range between 100°C-140°C when the resin layer is pressed via a smoothing plate in a reduced pressure environment. Accordingly, independent claim 1 (as amended) should now be clearly distinguished from Murakami.

Based on the above discussion, independent claim 1 (as amended) is not anticipated or rendered obvious by Murakami. Likewise, claims 2-11 are not anticipated or rendered obvious by Murakami at least by virtue of their dependencies (directly or indirectly) from independent claim 1.

In light of the above, the Applicant submits that all the pending claims are patentable over the prior art of record. The Applicants respectfully request that the Examiner withdraw the rejections presented in the outstanding Office Action, and pass the application to issue.

The Examiner is invited to contact the undersigned attorney by telephone to resolve any remaining issues.

Respectfully submitted,

Keiichi MURAKAMI

/Mark D. Pratt/

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Mark D. Pratt

Registration No. 45,794

Attorney for Applicant

MDP/ekb

Washington, D.C. 20005-1503

Telephone (202) 721-8200

Facsimile (202) 721-8250

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